

EL979955409



Application Serial No. 09/148,723
Response to December 16, 2003 Final OA

MI22-981

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/148,723
Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner A.D. Tugbang
Attorney's Docket No. MI22-981
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate

RESPONSE TO DECEMBER 16, 2003 FINAL OFFICE ACTION
PURSUANT TO 37 C.F.R. §1.116

To: Mail Stop AF
Commissioner for Patents
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Responsive to the Final Office Action dated December 16, 2003, Applicant amends and remarks as follows:

AMENDMENTS

Underlines indicate insertions and ~~strikeouts~~ indicate deletions.